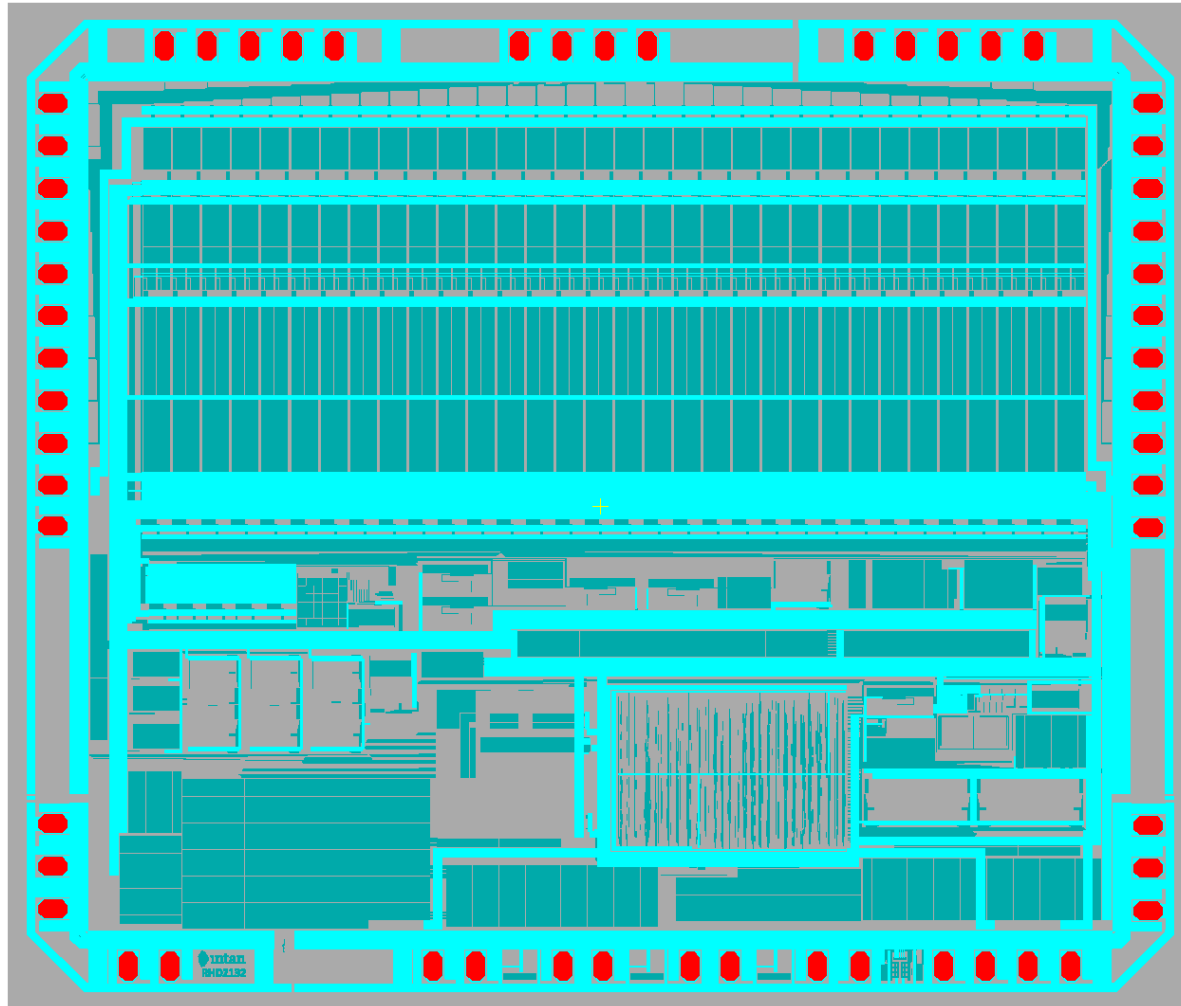
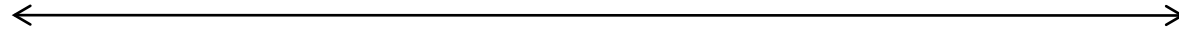


Intan Technologies RHD2132 Bare Die

Approximately 4.8 mm



Gray = approximate outline of die (may vary from die to die due to variations in sawing)

Yellow Cross = center of design (may not coincide precisely with center of die due to variations in sawing)

Blue, Green = top metal layers (highly visible)

Red = glass openings for bond pads



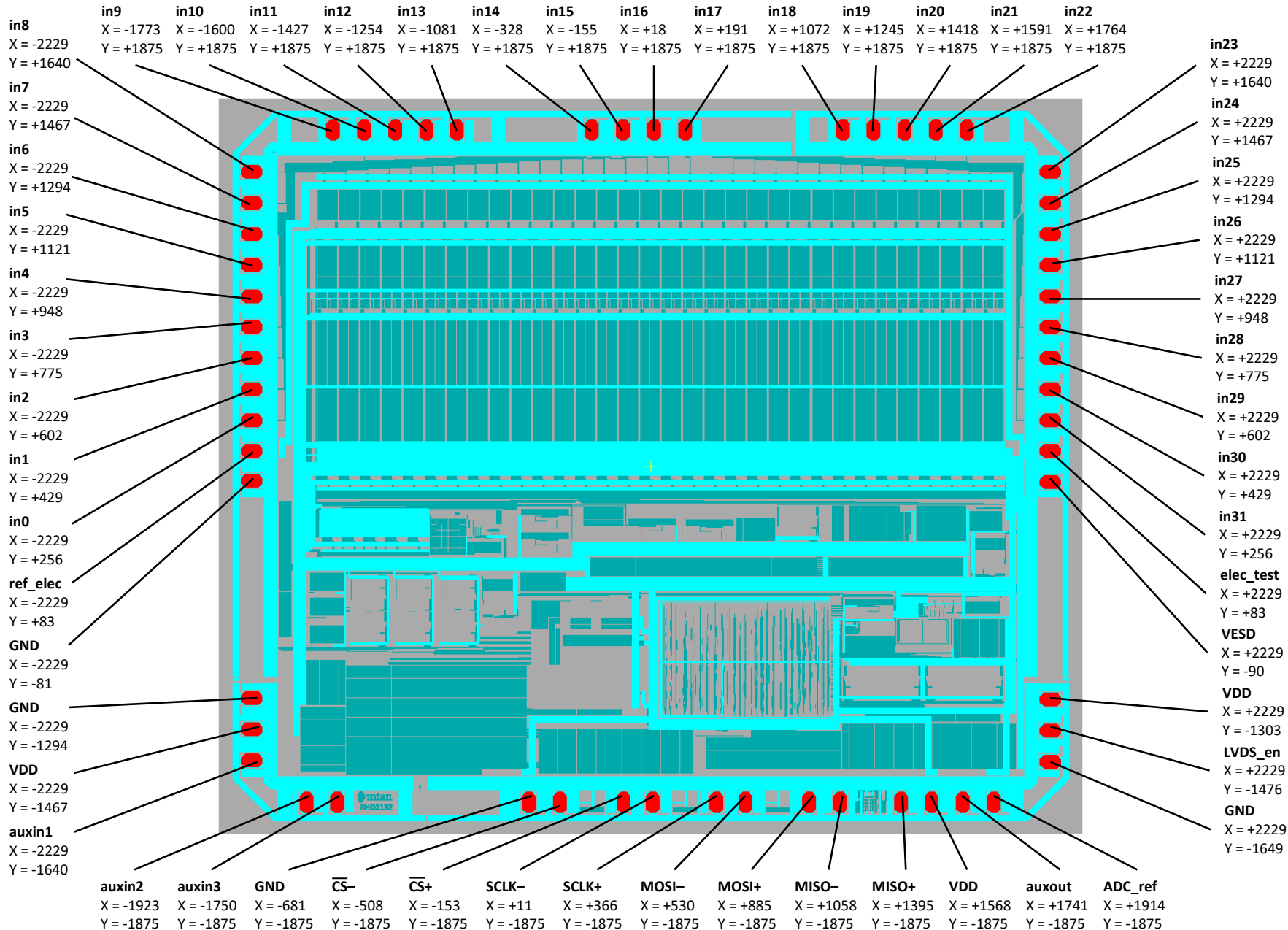
Approximately 4.1 mm

Each die is 0.20 mm (8 mils) thick

RHD2132

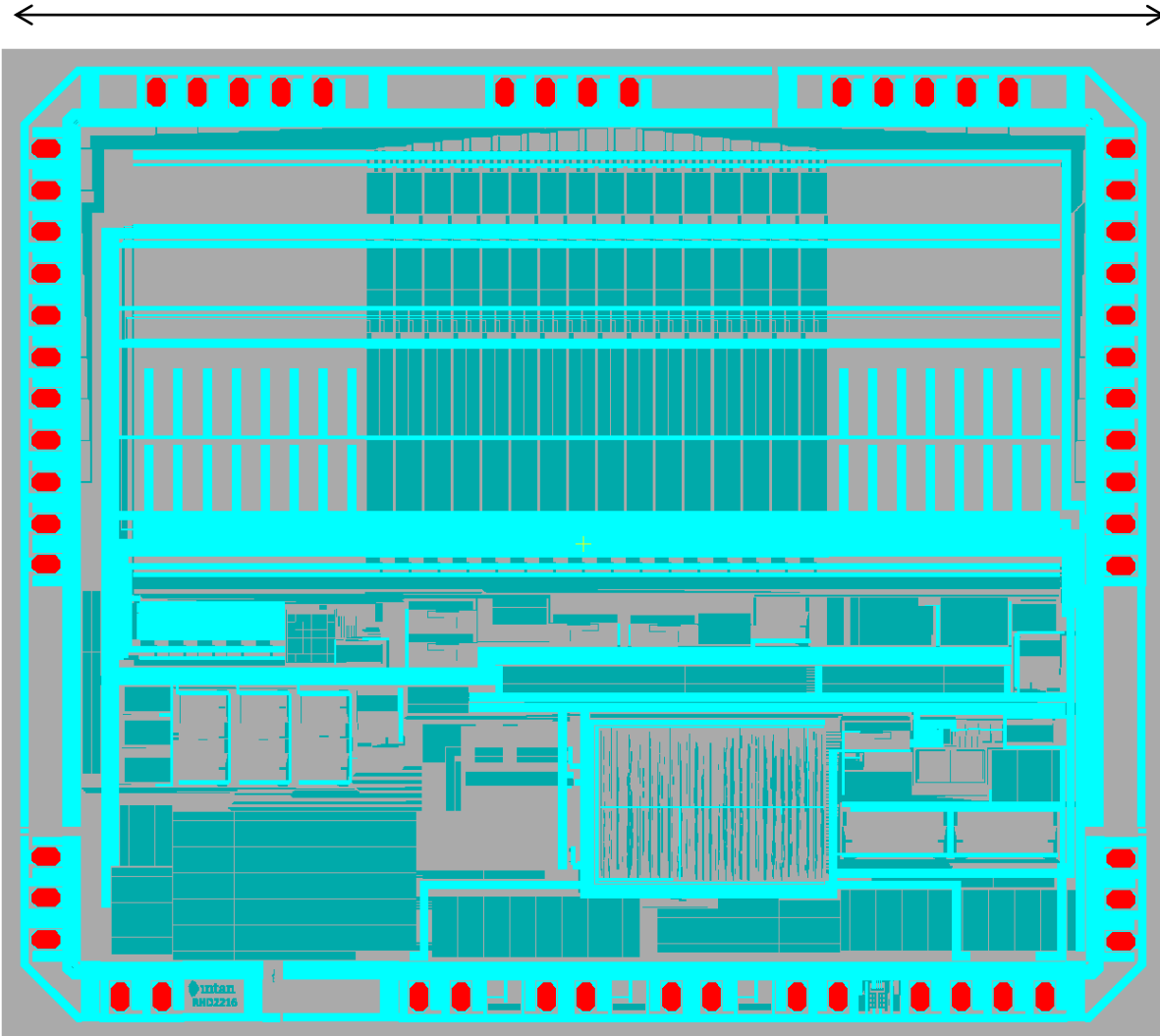
Coordinates of Bond Pad Centers, Relative to Center of Design

dimensions in microns



Intan Technologies RHD2216 Bare Die

Approximately 4.8 mm



Gray = approximate outline of die (may vary from die to die due to variations in sawing)

Yellow Cross = center of design (may not coincide precisely with center of die due to variations in sawing)

Blue, Green = top metal layers (highly visible)

Red = glass openings for bond pads

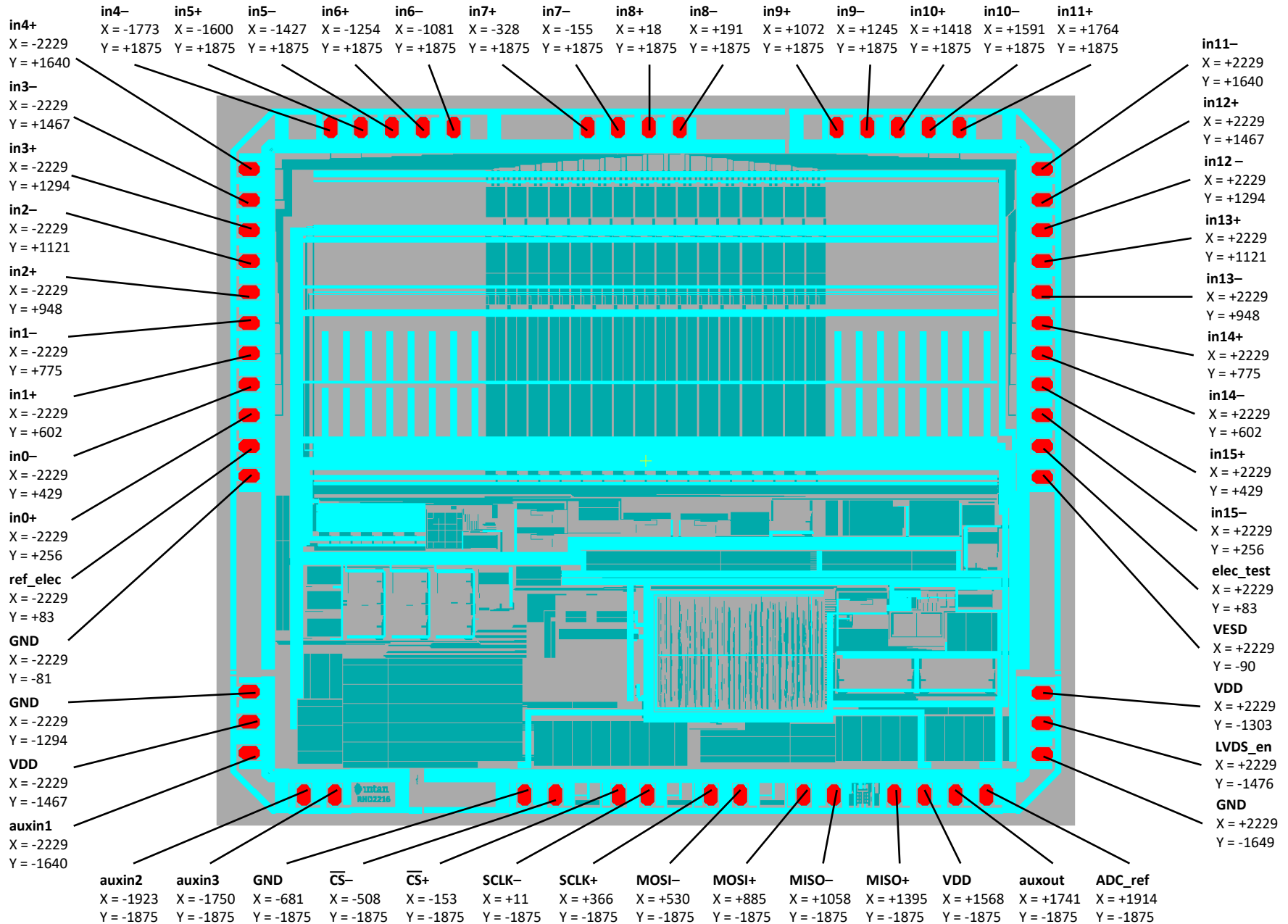
Approximately 4.1 mm

Each die is 0.20 mm (8 mils) thick

RHD2216

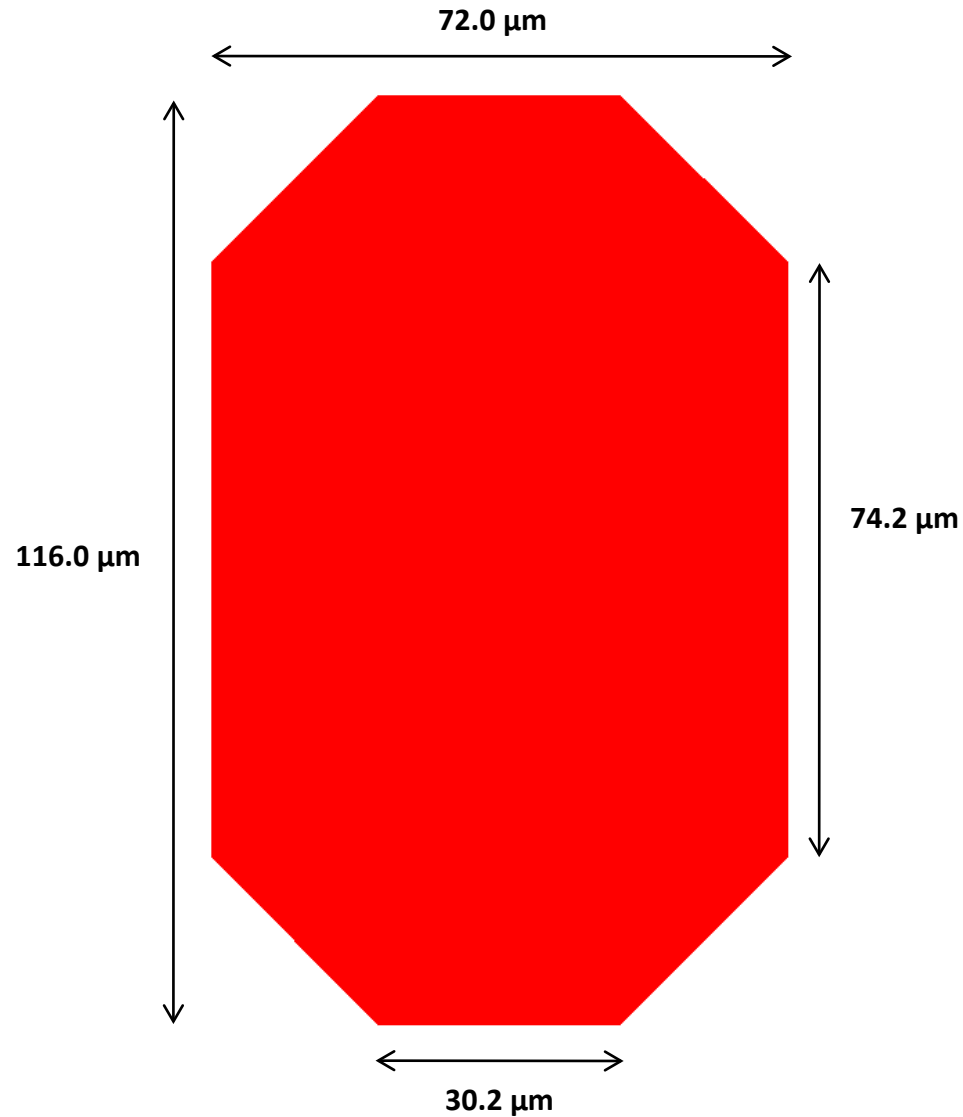
Coordinates of Bond Pad Centers, Relative to Center of Design

dimensions in microns



Bond Pad Dimensions

Bond pad metal: AlCu (99.5% aluminum, 0.5% copper) Thickness: 2.9 μm



Minimum bond pad pitch (center to center) on 16- and 32-channel chips: 164 μm